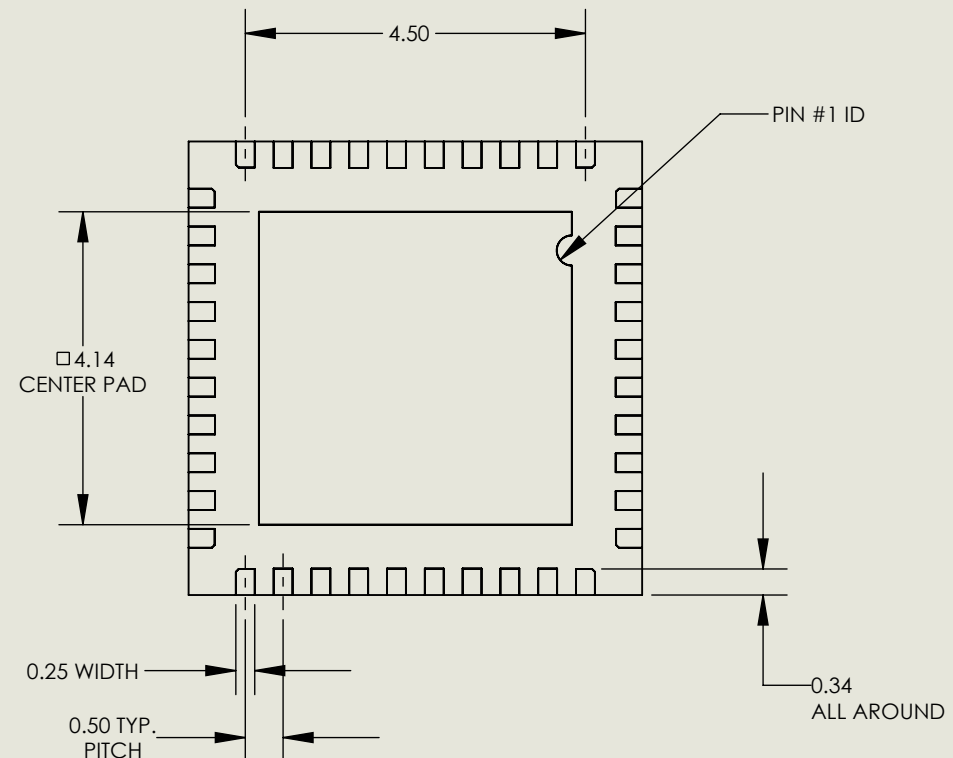
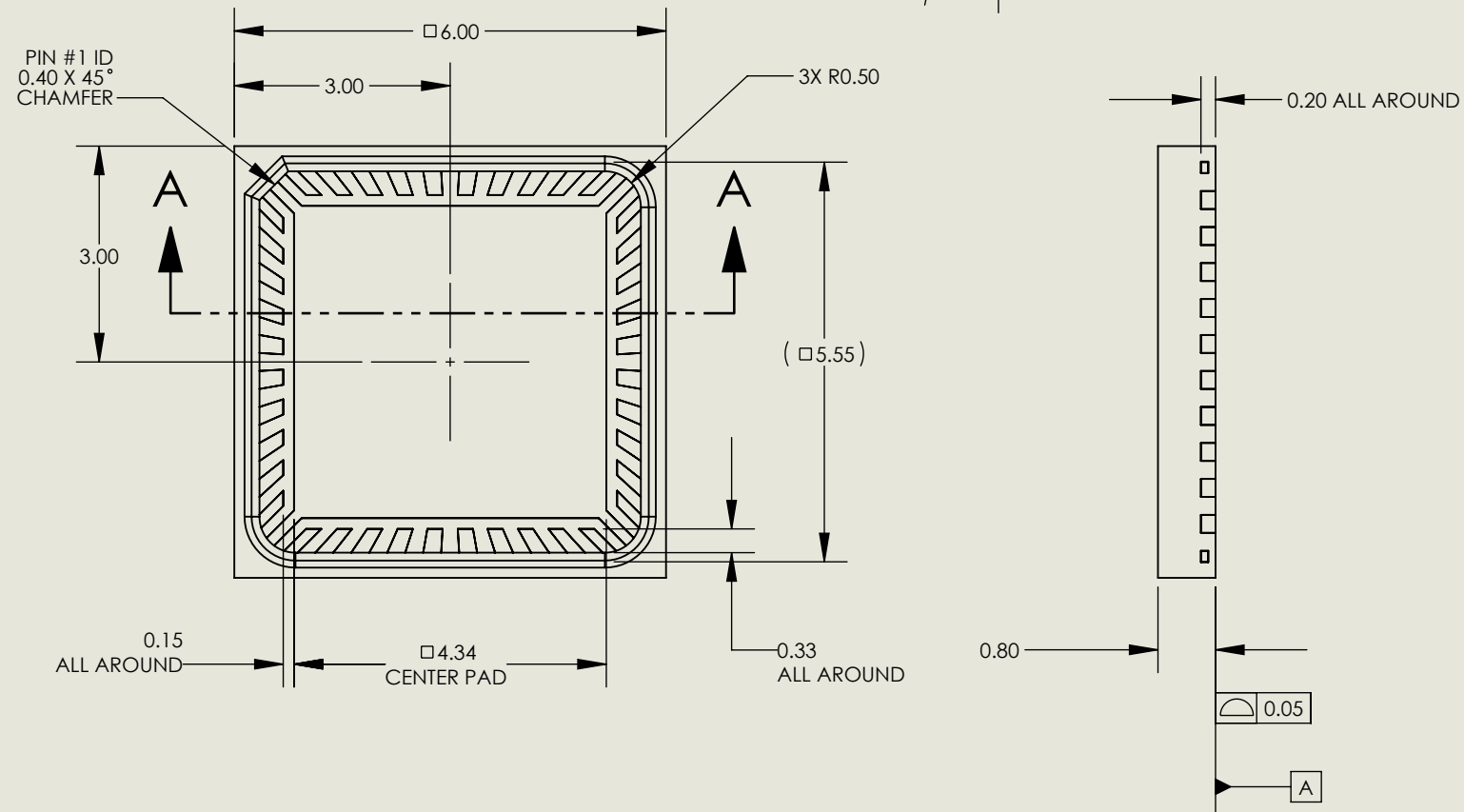
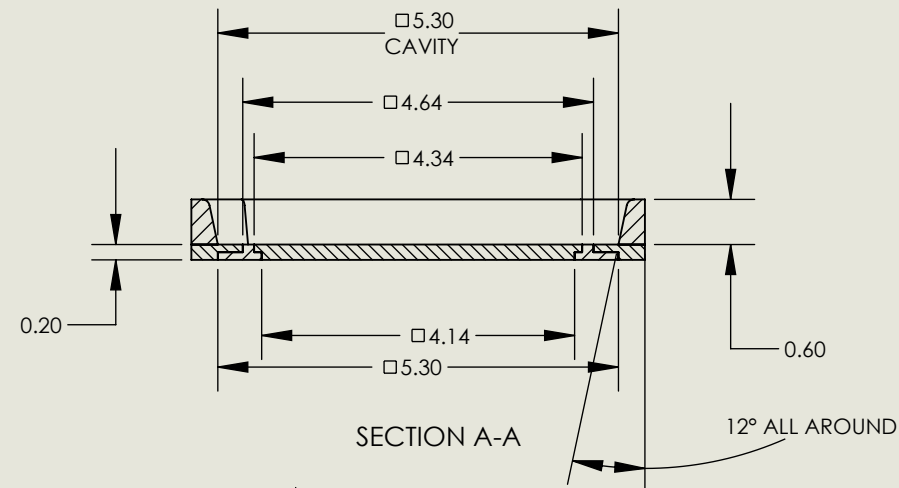
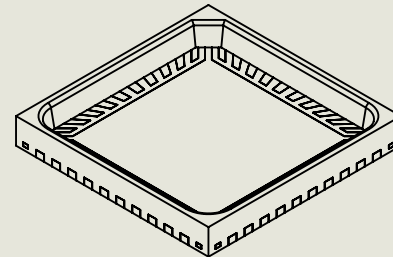


REVISIONS					
ZONE	REV.	DESCRIPTION	DATE	APPROVED	ECN NO.
	A	ORIGINAL RELEASE	8/3/11	SS	



NOTES

1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
200 TO 300 MICROINCHES (2.5 μ m-7.6 μ m) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
(40 TO 80 MICROINCHES (1 μ m-2 μ m) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO-220



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		UNLESS OTHERWISE SPECIFIED:		NAME	DATE	 QPTechnologies A DIVISION OF PROMEX INDUSTRIES QPTECHNOLOGIES.COM		
		DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:	DRAWN	D. Abbe	8/3/11	TITLE: QP-QFN40-6MM-0.50MM		
		ANGULAR: ±0.5 degree .X = ±0.10 .XX: ±0.05	CHECKED	S. Swen	8/3/11			
			ENG APPR.	S. Swen	8/3/11			
E		MATERIAL	COMMENTS:			SIZE	DWG. NO.	REV
		SEE NOTE 1				B	500388	A
NEXT ASSY	USED ON	FINISH						
APPLICATION		DO NOT SCALE DRAWING				SCALE: 10:1	WEIGHT:	SHEET 1 OF 1